Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	378	(semiconductor or die or chip or Ic) and (dielectric or insulat$3) and (copper or "Cu") with (plug or via or interconnect$3 or hole) and barrier with select$5 with deposit$3	USPAT	OR	OFF	2005/03/30 16:59
L2	145	(semiconductor or die or chip or Ic) and (dielectric or insulat$3) and (copper or "Cu") with (plug or via or interconnect$3 or hole) and barrier with selectively with deposit$3	USPAT	OR	OFF	2005/03/30 17:00
L3	26	(semiconductor or die or chip or Ic) and (dielectric or insulat$3) and (copper or "Cu") with (plug or via or interconnect$3 or hole) and barrier with selectively with deposit$3 same (electrolytic or electroplat$3 or electroless)	USPAT	OR	OFF	2005/03/30 18:23
L4	5	(semiconductor or die or chip or Ic) and (dielectric or insulat$3 or damasc$3) and (copper or "Cu") with (plug or via or interconnect$3 or hole) and barrier with selectively with deposit$3 same (electrolytic or electroplat$3)	USPAT	OR	OFF	2005/03/30 18:24
L5	7	(semiconductor or die or chip or Ic) and (dielectric or insulat$3 or damasc$3) and (copper or "Cu") with (plug or via or interconnect$3 or hole) and (barrier or cap$4) with selectively with deposit$3 same (electrolytic or electroplat$3)	USPAT	OR	OFF	2005/03/30 19:08
L6	75	(semiconductor or die or chip or Ic) and (dielectric or insulat$3 or damasc$3) and (copper or "Cu") with (plug or via or interconnect$3 or hole) and (barrier or cap$4) with ("Ru" or Ruthenium)	USPAT	OR	OFF	2005/03/30 19:52
L7	15	(semiconductor or die or chip or Ic) and (dielectric or insulat$3 or damasc$3) and (copper or "Cu") with (plug or via or interconnect$3 or hole) and (barrier or cap$4) with ("Ru" or Ruthenium) same ("Co" or cobalt)	USPAT	OR	OFF	2005/03/30 20:19
L8	0	"6395607".pn. and blanket	USPAT	OR	OFF	2005/03/30 20:59

L9	831	438/652	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/30 21:34
L10	462	438/654	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/30 21:34